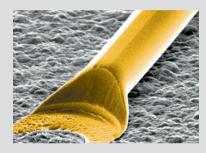
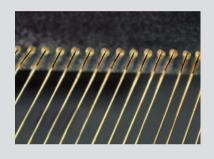
## Heraeus

# Au HD2 4N Gold Bonding Wire for Universal Use



The HD2 type, doped with a few ppm beryllium, is a standard wire for most modern bonding technologies in normal and high speed ranges. Due to its high loop stability, elevated temperature strength and ductility it can be used in most currently utilized components.

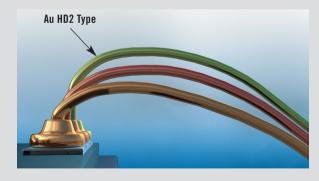


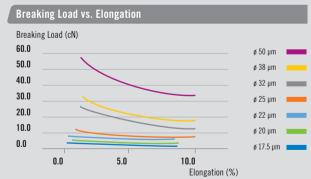
### Areas of application

- Discrete components (SOT, TO, ...)
- Integrated circuits (P-DIP, PLCC, SOIC, QFP, ...)
- COB (Chip-on-board)

#### Au HD2 Benefits

- Universal wire
- Soft type bonding wire of high ductility
- Exact loop guiding
- High loop stability
- Good thermal stability
- Suitable for all high performance bonding machines
- For normal and high speed assembling



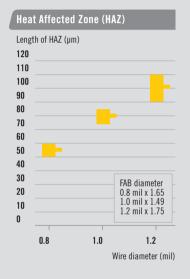


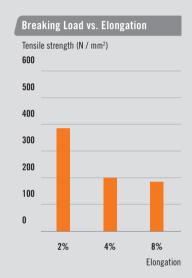
Recommended Technical Data of Au HD2									
Diameter	Microns (µm)	17.5	20	23	25	30	33	38	50
	Mils	0.7	0.8	0.9	1.0	1.2	1.3	1.5	2.0
Elongation	%	2 – 5	2 – 6	2 – 8	2 – 8	3 – 8	3 – 8	3 – 8	3 – 8
Breaking Load	cN	> 4	> 5	> 6	> 8	> 10	> 11	> 15	> 30

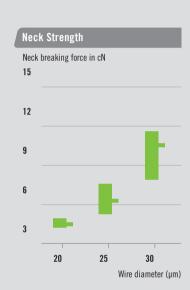
For other diameters, please contact Heraeus Bonding Wires sales representative.

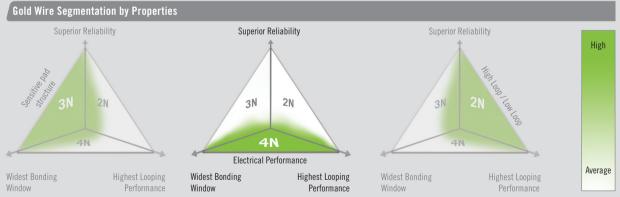
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HD2 Characteristics for 25 μm diam	eter		
Non-Gold Elements	< 100 ppm	Heat Conductivity	3.12 W / cm·K
Elastic Modulus	> 60 GPa	Electrical Resistivity	2.3 μ <b>Ω</b> -cm
Heat Affected Zone (HAZ)	190 – 230 μm	Coeff. of Linear Expansion (20 – 100 °C)	14.2 ppm / K
Melting Point	1063 °C	Fusing Current for 25 µm, dia 10 mm length (in air)	0.369 A
Density	19.32 g / cm <sup>3</sup>		









#### **Heraeus Electronics**

Heraeus Deutschland GmbH & Co. KG Heraeusstraße 12-14 63450 Hanau, Germany www.heraeus-electronics.com

#### **Americas**

Phone +1 610 825 6050 electronics.americas@heraeus.com

#### **Asia Pacific**

Phone +65 6571 7677 electronics.apac@heraeus.com

#### China

Phone +86 21 3357 5457 electronics.china@heraeus.com

### **Europe, Middle East and Africa**

Phone +49 6181 35 3069 +49 6181 35 3627 electronics.emea@heraeus.com

The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application.